

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3817	(dcb (direct with (copper u) with (bond bonding bonded)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 09:46
L2	2	latent with (heat heated heating) with (storage storing stored) and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 09:47
L3	2	(latent with (heat heated heating) with (storage storing stored)) and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 09:47

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	890	latent with (heat heated heating) with (storage storing stored) with (module medium device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 07:53
L2	6655271	(die chip ic (integrated adj circuit) semiconductor component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 07:54
L3	149	1 and 2 and (heat with (sink body dissipate dissipating dissipation dissipated radiate radiation radiated radiating spreader element metal))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 07:57